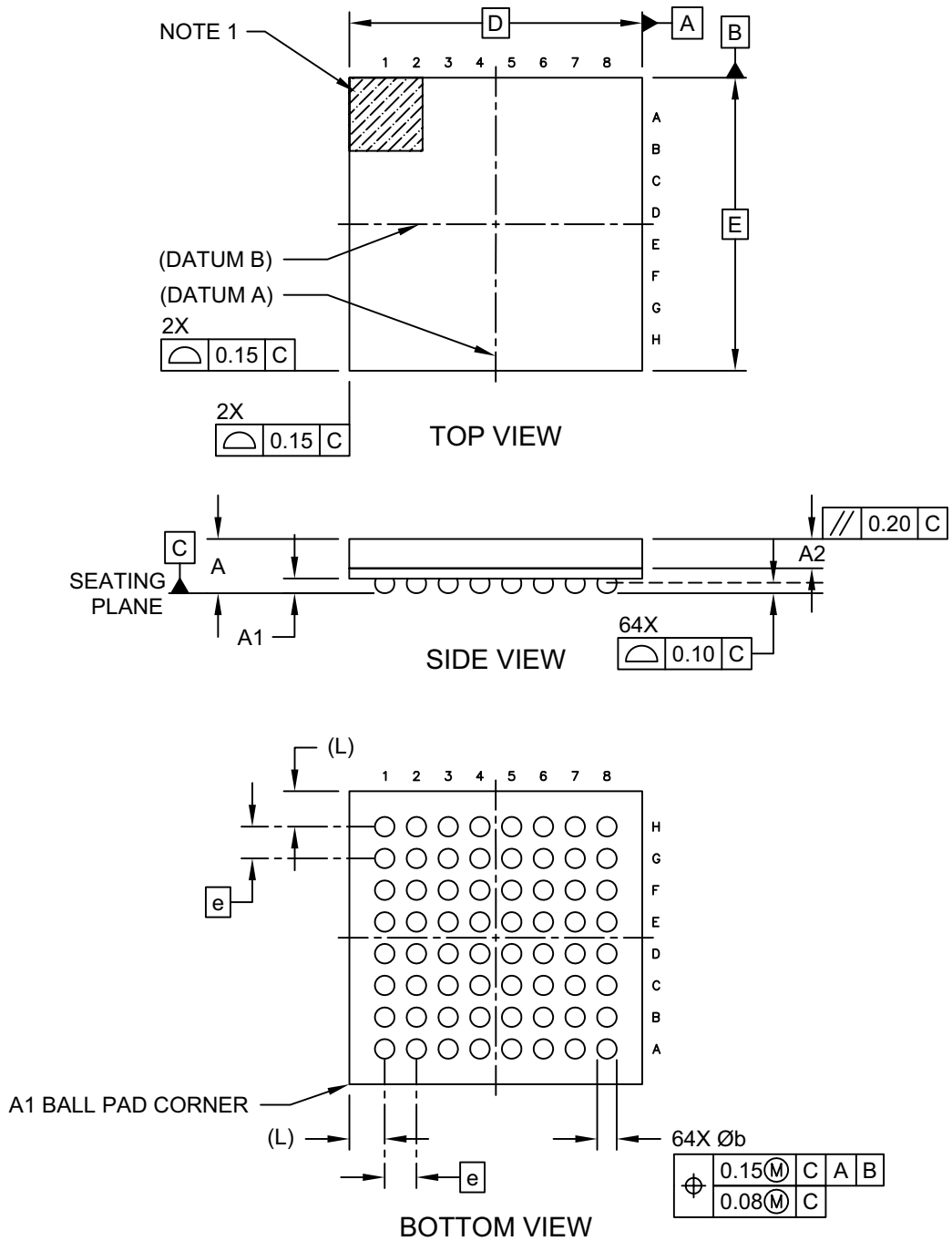


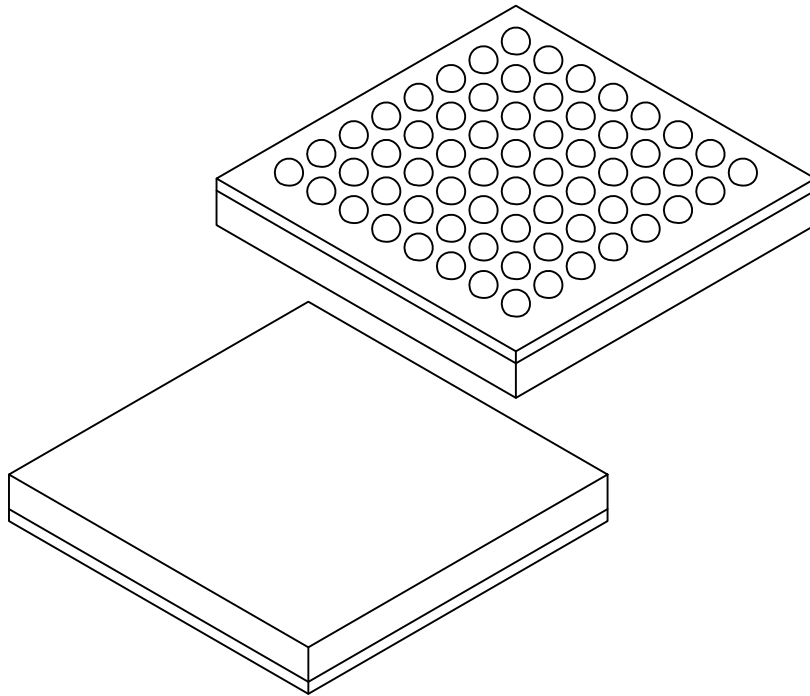
64-Lead Thin, Fine Pitch Ball Grid Array Package (7JX) - 6x6 mm Body [TFBGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



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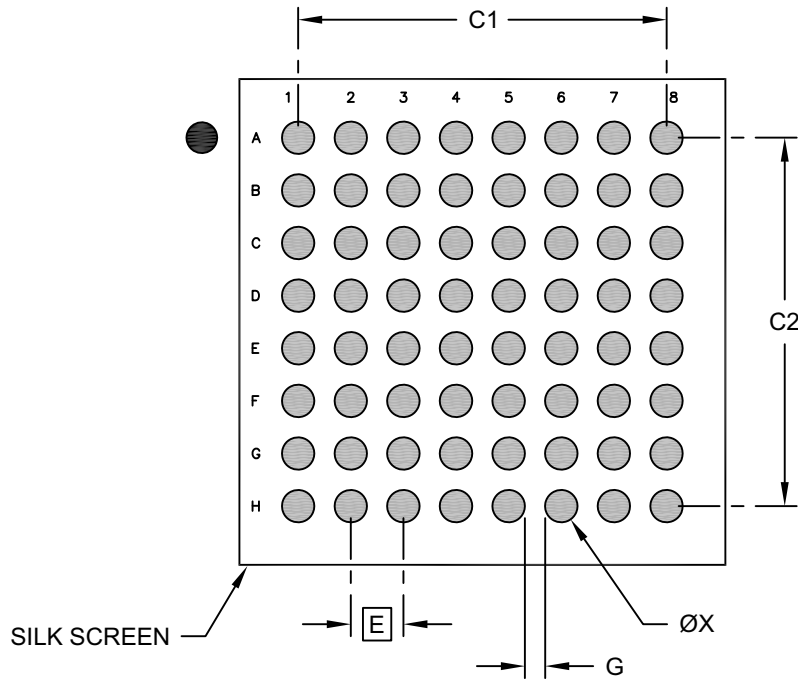
		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N	64		
Pitch	e	0.65 BSC		
Overall Height	A	-	-	1.20
Ball Height	A1	0.21	0.30	-
Mold Cap Thickness	A2	0.55	0.60	0.65
Overall Length	D	6.00 BSC		
Overall Width	E	6.00 BSC		
Terminal Ball Diameter	b	0.35	0.40	0.45
Edge to Ball Center	(L)	0.725 REF		

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensioning and tolerancing per ASME Y14.5M
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.

64-Lead Thin, Fine Pitch Ball Grid Array Package (7JX) - 6x6 mm Body [TFBGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Contact Pad Spacing	C1		4.55	
Contact Pad Spacing	C2		4.55	
Contact Pad Diameter (X64)	X			0.40
Space Between Pads	G	0.20		

Notes:

- Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.